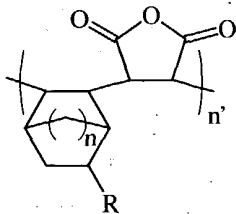


AMENDMENTS TO THE CLAIMS

Claims 1-18 (Cancelled)

- 1 19. (currently amended) A method of fabricating a device, comprising:
2 fabricating an integrated circuit chip, the integrated circuit chip including
3 a plurality of electrical bond pads;
4 fabricating a substrate;
5 positioning the integrated circuit chip relative to the substrate;
6 providing electrical connection between the integrated circuit chip and the
7 substrate during a reflow operation;
8 providing an underfill composition between the integrated circuit chip and the
9 substrate, the underfill composition including
10 a resin; and
11 a curing agent selected from the group consisting of maleic anhydride
12 polymers, maleic anhydride oligomers, maleic anhydride copolymers,
13 and a mixture thereof, having the formula:



14 in which R is selected from the group consisting of alkyl, aryl,
15 substituted aryls, esters, ethers, lactones, anhydrides, alcohols, nitriles,
16 epoxy, and mixtures thereof.

1 20. (original) The method according to claim 19 wherein the underfill composition is
2 provided simultaneously during reflow.

1 21. (original) The method according to claim 19 wherein the underfill composition is
2 provided after reflow.

1 22. (original) The method according to claim 19 wherein the underfill composition is
2 cured.

1 23. (original) The method according to claim 22 wherein the curing occurs within a
2 temperature range of from about 130° C to about 170° C. A method according to
3 claim 22 wherein the curing occurs within about 5 minutes to about 4 hours.

1 24. (original) A method according to claim 22 wherein the curing occurs within about
2 5 minutes to about 4 hours.